

## **Materials Declaration Form**

IPC	1752	Version	2					
Form Type *	Distribute	version	2					
Sectionals *	Material Info	Subsectionals *	A-D					
	Manufacturing Info		* : Required Field					
Supplier Information								
Company Name *	STMicroelectronics	Response Date *	31-10-2023					
Company Unique ID	NL 008751171B01							
Contact Name *	Refer to Supplier Comment section	-	Refer to Supplier Comment section					
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section					
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion					
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section					
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support.html							
			ocument and its contents are provided on a strict 'as is' and 'as available					
truth, accuracy, merchantability, fit		infringement. ST shall have no re	ntents, including but not limited to implied warranties of completeness esponsibility and assumes no liability for any cost, loss or damage of any ints.					

Supplier Acceptance *	true	Legal Declaration *	Standard	
Legal Statement	belief, as of the date that Supplier compl compliance of its products. Company ac form, and that Supplier may not ha independently verified information pro regarding their contributions to the part the Company and the Supplier enter that agreement, including any warranty	e provided information and such information is tr letes this form. Supplier acknowledges that Compan cknowledges that Supplier may have relied on info ave independently verified such information. Ho rovided by others, Supplier agrees that, at a mini t(s), and those certifications are at least as omprehe into a written agreement with respect to the in rights and/or remedies provided as part of that agr s remedies for issues that arise regarding informatio	ny will rely on this certification in deter promation provided by others in com- powever, in situations where Suppli- imum, its suppliers have provided c ensive as the certification in this p dentified part(s), the terms and co preement, will be the sole and exclusive	ermining the opleting this ier has not certifications aragraph. If onditions of

Product									
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date					
STM32F401CBU6 STM32F401CBU6TR	72MI*423XXXZ	А	998Z	31-10-2023					
	Amount	UoM	Unit type	ST ECOPACK Grade					
	102.52	mg	Each	ECOPACK <sup>®</sup> 2					
		ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)							

Manufacturing information							
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles					
3	260	3					
bulk Solder Termination	bulk Solder Termination Terminal Plating		Comment	life.augmented			
Not Applicable ; if coating is used or other bulk termaination : add in comments		Copper Alloy		monadgmonioa			

Package Designator	Package Designator Size		Shape	
QFN	7x7x0.55	48	flat	
Comment	Package : A0B9 UFQFPN 7X7X0.55 48L	0.5 MM PITCH 8202210		

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015							
Query Re							
1 - Product(s) meets EU RoHS requiremen	t without any exemptions	TRUE					
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)							
3 - Product(s) meets EU RoHS requirement	3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s) FALSE						
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions							
Exemption Id. Description							

QueryList : REACH-14th June 2023									
Query									
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH									
CategoryLevel_Name CategoryLevel_Threshold amount in product (mg) Application									

Interial Composition Declaration : ote : Substance present with less 0.001mg will not be declared in this document		Mfr Item Name	72MI*423XXXZ				6000000.0	1000007.8				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	2.527	mg	supplier	die	Silicon (Si)	7440-21-3		2.110	mg	834982	20582
				supplier	metallization	Aluminium (Al)	7429-90-5		0.029	mg	11476	283
				supplier	metallization	Copper (Cu)	7440-50-8		0.190	mg	75188	1853
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	396	10
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.026	mg	10289	254
				supplier	metallization	Tungsten (W)	7440-33-7		0.085	mg	33637	829
				supplier	Passivation	Silicon Nitride	12033-89-5		0.022	mg	8706	215
				supplier	Passivation	Silicon Oxide	7631-86-9		0.064	mg	25326	624
Glue Epoxy (8290)	M-011 Other inorganic materials	0.859	mg	Supplier	Metals	Silver (Ag)	7440-22-4		0.735	mg	855000	7166
				Supplier	Plastics/polymers	Epoxy resin 1	Trade Secret		0.017	mg	20000	168
				Supplier	Organic Compounds	Epoxy resin 2	Trade Secret		0.017	mg	20000	168
				Supplier	Organic Compounds	.gammaButyrolactone	96-48-0		0.026	mg	30000	251
				Supplier	Organic Compounds	Epoxy resin 3	Trade Secret		0.017	mg	20000	168
				Supplier	Organic Compounds	Amine	Trade Secret		0.017	mg	20000	168
				Supplier	Metallic compounds	Copper oxide	1317-38-0		0.026	mg	30000	251
				Supplier	Organic Compounds	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		0.004	mg	5000	42
Encapsulation (EME G770)	M-011 Other inorganic materials	36.281	mg	Supplier	Organic Compounds	Epoxy Resin A	Trade Secret		0.762	mg	21000	7432
				Supplier	Organic Compounds	Epoxy Resin B	Trade Secret		0.762	mg	21000	7432
				Supplier	Organic Compounds	Phenol Resin A	Trade Secret		0.762	mg	21000	7432
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		28.316	mg	780450	276199
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		4.184	mg	115320	40811
				Supplier	Organic Compounds	Carbon Black	1333-86-4		0.226	mg	6230	2205
				Supplier	Metallic compounds	Metal Hydroxide	Trade Secret		0.508	mg	14000	4955
				Supplier	Organic Compounds	Phenol Resin B	Trade Secret		0.762	mg	21000	7432
Gold Wire (Au)	Bonding Wire	0.742	mg	Supplier	Metals	Gold (Au)	7440-57-5		0.742	mg	1000000	7238
Plating (Sn)	M-011 Other inorganic materials	1.078	mg	Supplier	Metals	Tin (Sn)	7440-31-5		1.078	mg	1000000	10519
Leadframe (C7025 + Ag)	Copper & its alloys	61.032	mg	Supplier	Metals	Copper (Cu)	7440-50-8		55.975	mg	917140	545994
				Supplier	Metals	Nickel (Ni)	7440-02-0		1.373	mg	22500	13395
				Supplier	Metals	Silicon (Si)	7440-21-3		0.159	mg	2600	1548
				Supplier	Metals	Magnesium (Mg)	7439-95-4		0.070	mg	1150	685
				Supplier	Metals	Silver (Ag)	7440-22-4		3.455	mg	56610	33701